

# Chip Scale R E V I E W<sup>®</sup>

## OUR COLUMNISTS

### CHIP SCALE REVIEW PRESENTS COMPELLING AND TOPICAL EDITORIAL

*Chip Scale Review's* columns, commentary and features are written by internationally known and respected experts in a variety of semiconductor and semiconductor-related disciplines. These include IC assembly and packaging, test, electronics interconnection, MEMS and optoelectronics.

Nearly all contributed articles are original to *Chip Scale Review*. To ensure high quality and accuracy of content, contributed articles are sent to selected peer reviewers, who read and anonymously critique each article. The reviewers also grade each contributed article on its likely value to *Chip Scale Review* readers.



Iscoff



Thompson

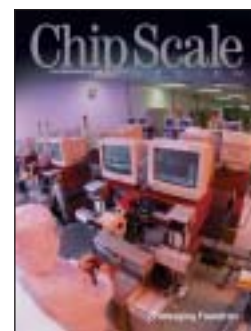
Our chief editorial staff is composed of Editor Ron Iscoff, and Senior Editor Terrence E. "Terry" Thompson, who form one of the most experienced combinations in semiconductor trade journalism.

Together, they bring more than 50 years experience in covering the semiconductor industry to *Chip Scale Review*. Ron is the founding editor of the magazine and has been in charge of editorial content since the first issue rolled off the press in May 1997. Prior to *Chip Scale Review*, he was an editor for *Electronic Packaging & Production*, *Semiconductor International*, *CAE Report*, and a reporter for *Electronic News*.

Terry brings an equally impressive list of credentials to *Chip Scale Review*. In addition to his posts as editor of *Assembly* magazine and editorial director of both *Microelectronic Manufacturing & Testing* and *Hybrid Circuit Technology*, he was also executive editor for *Solid State Technology* and *MicroLithography World*. Prior to joining *Chip Scale Review*, Terry was also founding editor-in-chief of *HDI* magazine. Terry has been a speaker at important industry events, including the APiA and SECAP conferences.



Unlike most publishers of semiconductor-industry magazines, *Chip Scale Review* Publisher Gene Selven has spent most of his career in the semiconductor industry. His experience includes senior marketing management posts at Fairchild, Raytheon Semiconductor and Texas Instruments. Prior to acquiring *Chip Scale Review* in 1999, Gene was Founder/Editor/Publisher of Electronic Trend Publications Inc., a successful Silicon Valley semiconductor research firm. Gene's vast experience in the industry enables him to make substantial contributions to the magazine's editorial mission.



Our contributing editors are unmatched, as well, beginning with Dr. Tom Di Stefano, Senior Contributing Editor.



Tom is virtually synonymous with wafer-level and chip-scale packaging. A true pioneer in the field, Tom is a much-in-demand speaker, consultant and a prolific author with many patents to his credit. He was the founder of Tessera, and earlier spent nearly two decades as a senior manager at IBM. His column, "Wafer-Level Watch," reviews the latest technology trends and explains how they will impact the industry and our readers. Tom was also founding publisher of *Chip Scale Review*.

## OUR COLUMNISTS

### Features

Each issue contains a diverse selection of feature articles. One or more topics are selected for special emphasis in each issue because of their timeliness and importance to readers.

Each issue of *Chip Scale Review* is meticulously prepared to be the authoritative publication on the featured topics. Our editorial calendar, available by mid-September for the following year, represents a roadmap for our readers, advertisers, contributors and staff. Year after year, *Chip Scale Review* prints more original, staff-written articles than any competitive publication in our field.

### An Expert Looks at the Issues™

Experts discuss key issues surrounding a topic of immediate and widespread interest to our readers. This department appears in selected issues throughout the year.

### Tools & Technologies™

This department, edited and assembled by the staff of *Chip Scale Review*, showcases the newest products and processes in the IC assembly, packaging and test areas. Products are selected from the dozens of product releases sent to us by the vendor community.

### Vendor Directories

Each issue of *Chip Scale Review* features extensive vendor product directories. These directories accompany feature articles on specific topics.

For example, if we publish a feature on test-and-burn-in sockets, we will also publish a directory of socket vendors at the end of the article. These special directories are unique to *Chip Scale Review*.

Unlike simple vendor lists in other publications, our directories contain substantial comparative product data supplied by the manufacturers.

Because of their completeness, these listings enable our readers to “comparison shop” and then to contact the specific vendor of a product that meets the reader’s needs.

### Emerging Technologies

This contributed feature examines breakthroughs in equipment, materials or processes. The developers discuss its significance and attributes, the strategy behind its development, and how it works. Companies that believe that have an important candidate for this department are invited to contact the editor.

### Tutorials

Our ongoing series of tutorials is specially prepared for *Chip Scale Review* by the leading authorities on the tutorial topic. They are written and edited to be useful even to occasional readers, such as purchasing agents or technicians, while providing valuable information to the engineering and OEM management community.

### Editorial Advisory Board

Our continued excellence depends on immediate and continuing feedback from our readers, advertisers and our Editorial Advisory Board. Composed of a cross-section of experts from several disciplines within semiconductors, and from several geographic regions, our advisors keep us on the leading edge of technology.



Steve Anderson  
Consultant  
Phoenix, Arizona



Richard Boulanger  
Universal Instruments Corp.  
Binghamton, N.Y.



Dr. Thomas Di Stefano  
Decision Track Inc.  
San Jose



Gil Olachea  
Kulicke & Soffa Flip Chip Division  
Phoenix, Arizona



Prof. Guna Selvaduray  
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Dr. Dietrich Tönnies  
Suss MicroTec GmbH  
Garching, Germany



Dr. Dan Tracy  
SEMI  
San Jose



Prof. C.P. Wong  
Georgia Institute of Technology  
Atlanta, Georgia

## OUR COLUMNISTS

### SPECIALTY COLUMNS BY EXPERTS ARE FEATURED IN EVERY ISSUE

**Chip Scale Review** features the best-known names in IC packaging and test in every issue. Columnists are experts on their topics and internationally known.

#### Assembly Lines™ by Ron Iscoff

Editor Ron Iscoff has been covering the international chip assembly and packaging industry for more than 25 years. Through his knowledge of the key players, and his widespread recognition throughout the industry, he is able to bring a special, unmatched insight to the issues that impact the IC subcontract community, its customers and its suppliers.

#### Opto-Electronically Speaking™ by Terrence E. Thompson

**Chip Scale Review** recognizes the growing importance of optoelectronic and MEMS packaging, and Senior Editor Terry Thompson follows this area with an unblinking eye. Will a new opto device or process be the next big thing or the next big nothing? Terry knows and distills the essence of his 25 years in the IC packaging industry into every word. Every issue features Terry's thoughtful and thought-provoking commentary on this expanding field.



#### Electronic Trends™ by Steve Berry and Sandra Winkler

Contributing Editors Steve Berry and Sandra Winkler are widely known for their incisive and comprehensive market research publications covering the semiconductor assembly and packaging

industry. Their column, which appears about six times a year, covers the business and economics of the IC assembly industry, with a special emphasis on future packaging technology trends.



#### Standards by Mark S. Bird

Mark Bird, our standards specialist, is an Amkor Technology Fellow with decades of experience in the semiconductor packaging industry. A veteran of numerous standards committees, Mark takes **Chip Scale Review** readers behind the scenes of standards battles and explains how and why packaging standards finally take shape.

#### Wafer-Level Watch™ by Dr. Tom Di Stefano

Tom takes readers through the processes and peregrinations of the expanding chip-scale and wafer-level packaging world, in which he has been a key player since its beginning, more than a decade ago.



#### Patents by David Francis and Linda Jardine

Industry researchers David Francis and Linda Jardine review hundreds of IC packaging patents each year to select the unique, the unusual, the important and the exceptional.

Their patent coverage, exclusive to **Chip Scale Review**, appears in each issue.



#### Packaging Insights™ by Lee Levine

If you need to know something about wire bonding or other methods of electrical interconnection, there are a handful of people who possess extensive knowledge of these areas. Lee Levine is one of the best. After spending more than a decade at Kulicke & Soffa Inc., where he developed many of the leading-edge technologies later incorporated into K&S wire bonders, Lee began his own consultancy. He now writes a column for **Chip Scale Review** several times a year.



#### The Flip Side™ by Gil Olachea

The president of a major producer of flip chips, Gil Olachea is at the forefront of this technology. Widely known throughout the IC assembly industry, Gil is a veteran of more than two decades with major packaging foundries, including Amkor Technology.



#### On Test™ by Paul Sakamoto

There isn't much that Paul Sakamoto, our resident test expert, doesn't know about test methods and equipment. Formerly vice president of memory test products at Credence Systems, Paul is now CEO at Inovys, a supplier of structural test systems. In his column, Paul interprets test trends with a great deal of wit, mixed with strong dollops of irony. His unflinching reportage makes his writing not only entertaining, but controversial, as well.



#### The View from Europe™ by Dr. Claudio Truzzi

Consultant Claudio Truzzi brings years of experience to his task as consultant and author. Writing from the Netherlands, Dr. Truzzi, a former vice president at CS2 and a specialist in semiconductor packaging, explores the packaging scene in Europe from his expert's vantage point.



#### Harvey Miller's Notebook by Harvey S. Miller

Mr. Miller is a near-legendary observer of the electronics and printed circuit board industries. He is an economist by education and an inquisitive engineer by training. Harvey is without parallel in his forecasts of industry trends. His articles often provoke, and sometimes irritate those in the industry who cling to the status quo, even as they inform in his own, trademarked style.

# Chip Scale

REVIEW

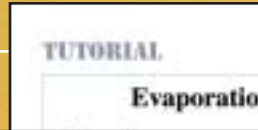
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